

# winDot F-005

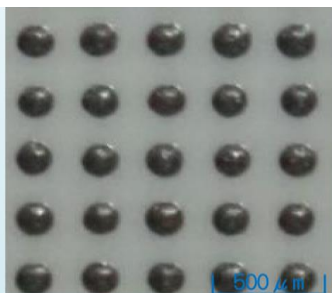
Made in JAPAN

Solder Paste developed for extremely small Jetting  
Extremely fine dispensing as well as good soldering results!

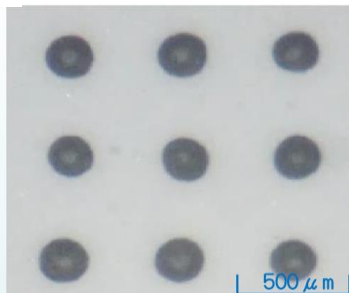
1. Solder paste for 200um or smaller dot sizes, high speed jetting
2. Designed for solder paste dispensing into cavity packages
3. Designed for solder paste dispensing for mixed size components
4. Solder paste for PCBs that are difficult to print on because of warpage or for dispensing onto lead frames

## Jet Dispensing Results:

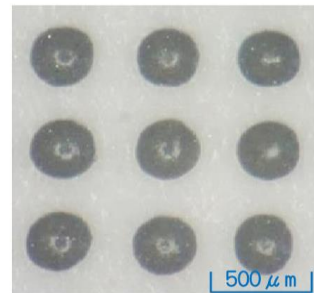
Jet Dispense shape & size:



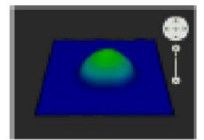
<  $\phi$  150  $\mu$  m



<  $\phi$  200  $\mu$  m

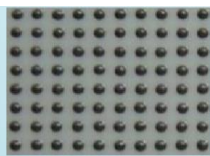


<  $\phi$  300  $\mu$  m

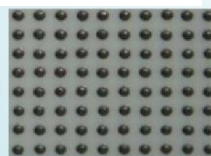


Jetted 3D Shape

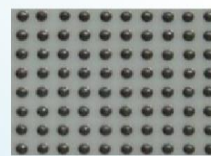
## Continuous Jetting Performance



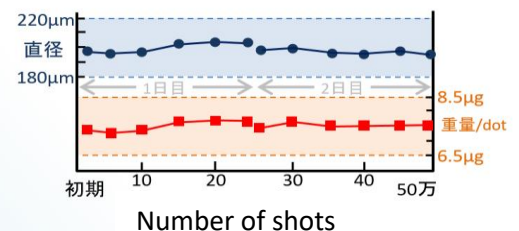
At Start



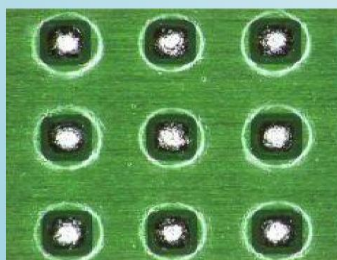
300,000



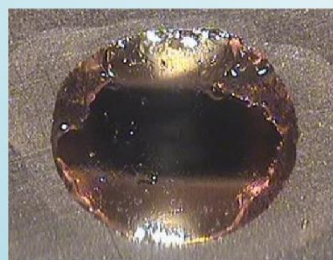
500,000



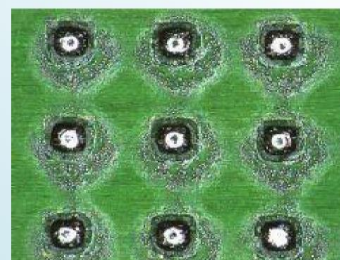
## Reflow Evaluation Results (O<sub>2</sub> = 1500ppm)



On Cu



On Ni



On Cu



On Ni

winDot

Competitor's Solder Paste

SAC305 type

NIHON GENMA MFG.CO.,LTD.

<https://www.genma.co.jp/>



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